

RAD-3000m/12



Outline

- -Semi-automatic BG Tape remover for mounted wafer.
- Removes back grinding tape by attaching heat seal on the periphery of the wafer, fixed with heater.

Suitable Tapes ·BG Tape : Adwill E series, P series

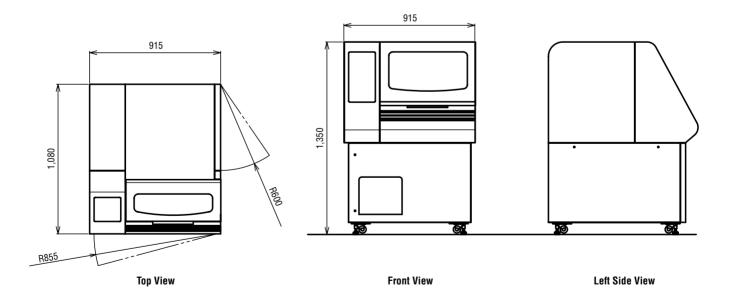
External View

Facility **Power Supply** Voltage : AC200-230V ±10% (AC190-253V) Frequency : 50/60Hz Phase : single phase Power consumption : 0.8kW Capacity : 3.0kW **Air Supply** Air pressure : 0.5-0.8MPa Air consumption :>150L/min (ANR) Applicable Wafer Size 200mm, 300mm Width: 915mm Size Depth: 1,080mm Height: 1,350mm Weight 250kg

30sec/wafer (excludes setting time)

Unit:mm

Processing Capacity





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